

### **General Description**

The WSR180N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSR180N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

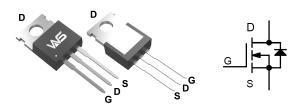
### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	$3.0 \text{m}\Omega$	180A

### **Applications**

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

### **TO-220AB Pin Configuration**



### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±25	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	180	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	90	Α
l <sub>DM</sub> Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°С		600	Α
EAS Avalanche Energy, Single pulse		545	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse	60	Α
P <sub>D</sub> @T <sub>C</sub> =25℃	P <sub>D</sub> @T <sub>C</sub> =25℃ Total Power Dissipation <sup>4</sup>		W
T <sub>STG</sub>	T <sub>STG</sub> Storage Temperature Range		$^{\circ}$
TJ	T <sub>J</sub> Operating Junction Temperature Range		$^{\circ}$

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		0.55	°C/W



### Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =1mA		0.096		V/°C	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =80A		3.0	4.0	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . In =250uA	2.5	3.0	4.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID -230UA		-5.5		mV/℃	
l	Drain Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA	
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =50A		120		S	
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		0.7	1.5	Ω	
Qg	Total Gate Charge (10V)			80			
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =80V , V <sub>GS</sub> =10V , I <sub>D</sub> =80A		33		nC	
$Q_gd$	Gate-Drain Charge			18			
T <sub>d(on)</sub>	Turn-On Delay Time			28			
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V ,		55			
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=5\Omega$ , $I_D=80A$		98		ns	
T <sub>f</sub>	Fall Time			24			
C <sub>iss</sub>	Input Capacitance			4120			
Coss	Output Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		1250		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			65			

### **Diode Characteristics**

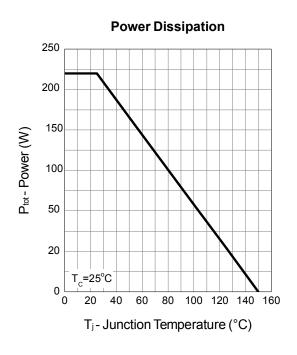
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			80	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =50A , T <sub>J</sub> =25℃		0.8	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I- 504 III 4004 - T 05°C		85		nS
Qrr	Reverse Recovery Charge	IF=50A,dI/dt=100A/µs,T <sub>J</sub> =25℃		200		nC

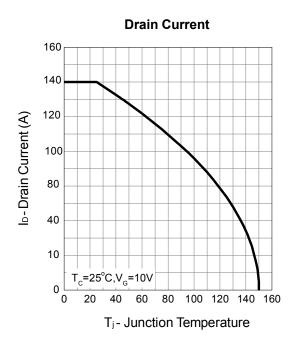
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec. 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2% 3.The EAS data shows Max. rating . The test condition is V<sub>DS</sub>=80V,V<sub>GS</sub>=10V,L=0.1mH,

- 5. The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

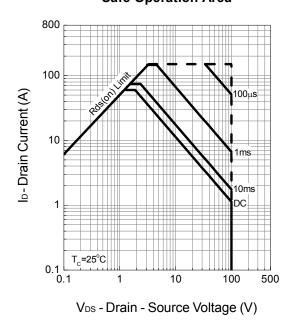


# **Typical Operating Characteristics**

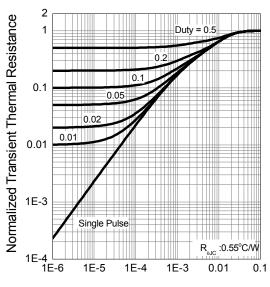




## **Safe Operation Area**



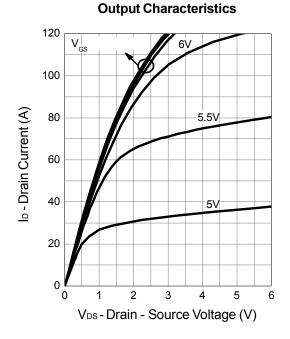
### **Thermal Transient Impedance**



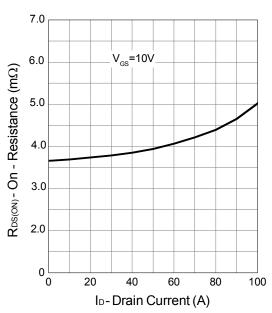
Square Wave Pulse Duration (sec)



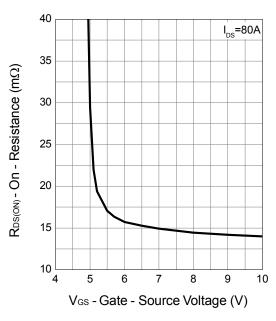
# **Typical Operating Characteristics (Cont.)**



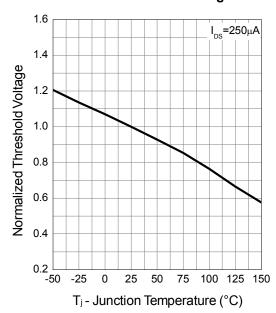
### **Drain-Source On Resistance**



### **Gate-Source On Resistance**



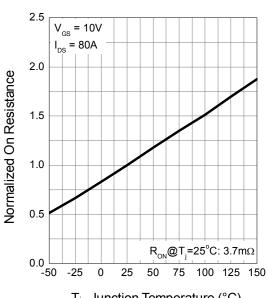
### **Gate Threshold Voltage**



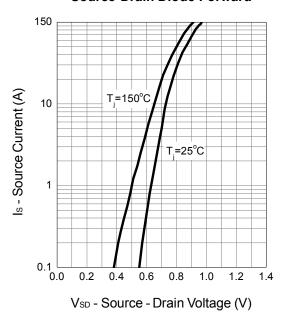


# **Typical Operating Characteristics (Cont.)**

# Drain-Source On Resistance

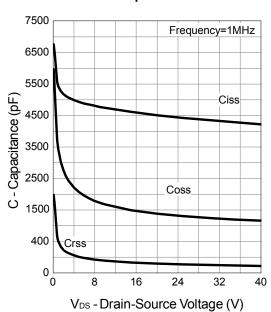


### Source-Drain Diode Forward

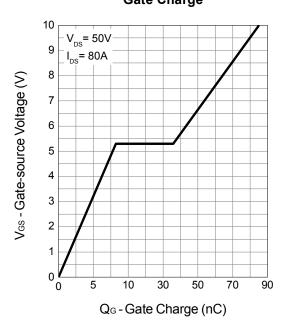


T<sub>j</sub>- Junction Temperature (°C)

### Capacitance

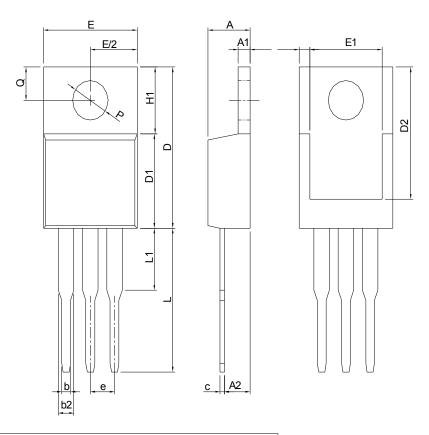


# **Gate Charge**



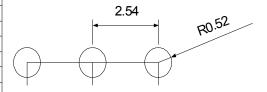


# Package Information TO-220AB



Ş	TO-220				
SYMBO	MILLIMI	ETERS	INC	HES	
5	MIN.	MAX.	MIN.	MAX.	
Α	3.56	4.83	0.140	0.190	
A1	0.51	1.40	0.020	0.055	
A2	2.03	2.92	0.080	0.115	
b	0.38	1.02	0.015	0.040	
b2	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.22	16.51	0.560	0.650	
D1	8.38	9.02	0.330	0.355	
D2	12.19	13.65	0.480	0.537	
Е	9.65	10.67	0.380	0.420	
E1	6.86	8.89	0.270	0.350	
е	2.54 BSC		0.100 BSC		
H1	5.84	6.86	0.230	0.270	
L	12.70	14.73	0.500	0.580	
L1		6.35		0.250	
Р	3.53	4.09	0.139	0.161	
Q	2.54	3.43	0.100	0.135	

### RECOMMENDED LAND PATTERN



UNIT: mm



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